

Small Signal Diode

MMBD4148SE, MMBD4148CC, MMBD4148CA

Features

• These are Pb-Free Devices

MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Maximum Repetitive Reverse Voltage	V_{RRM}	100	V
Average Rectified Forward Current	I _{F(AV)}	200	mA
Non-Repetitive Peak Forward Surge Current Pulse Width = 1.0 s Pulse Width = 1.0 μs	I _{FSM}	1.0 2.0	A
Operating Junction Temperature Range	TJ	150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	350	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	357	°C/W

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

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Characteristic	Symbol	Min	Тур	Max	Unit
Breakdown Voltage $I_R = 5.0 \ \mu A$ $I_R = 100 \ \mu A$	V _R	75 100	- 1	- 1	V
Forward Voltage I _F = 10 mA	V _F	_	1	1.0	٧
Reverse Leakage Current $V_R = 20 \text{ V}$ $V_R = 20 \text{ V}$, $V_A = 150 ^{\circ}\text{C}$ $V_R = 75 \text{ V}$	I _R			25 50 5.0	nA μA μA
Total Capacitance V _R = 0 V, f = 1.0 MHz	C _T	-	-	4.0	pF
Reverse Recovery Time I_F = 10 mA, V_R = 6.0 V, I_{RR} = 1.0 mA, R_L = 100 Ω	t _{rr}	-	-	4.0	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

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CONNECTION DIAGRAM





SOT-23 (TO-236) CASE 318-08

MARKING DIAGRAM



Dx = Device Code

x = 4, 5, 6

M = Assembly Operation Month

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MMBD4148SE, MMBD4148CC, MMBD4148CA

TYPICAL PERFORMANCE CHARACTERISTICS

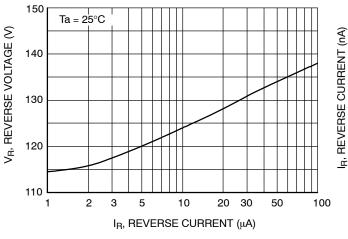


Figure 1. Reverse Voltage vs. Reverse Current BV - 1.0 to 100 μA

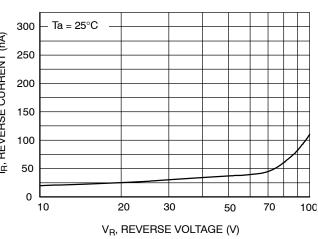


Figure 2. Reverse Current vs. Reverse Voltage IR – 10 to 100 V

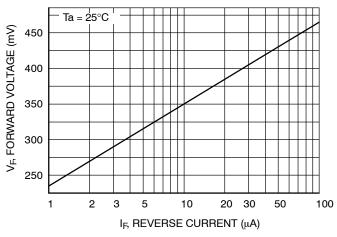


Figure 3. Forward Voltage vs. Forward Current VF - 1.0 to 100 μ A

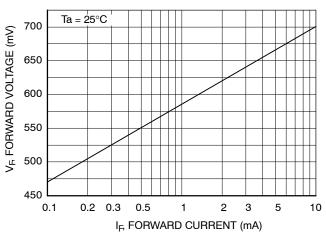


Figure 4. Forward Voltage vs. Forward Current VF – 0.1 to 10 mA

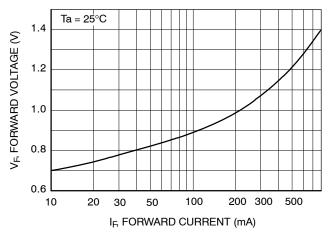


Figure 5. Forward Voltage vs. Forward Current VF – 10 to 800 mA

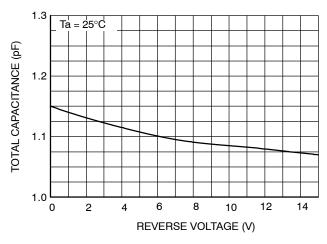


Figure 6. Total Capacitance vs. Reverse Voltage

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TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

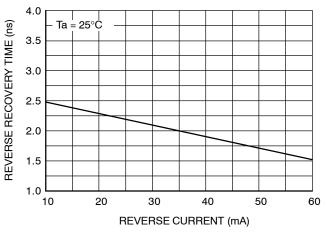


Figure 7. Reverse Recovery Time vs. Reverse Current TRR – IR 10 mA to 60 mA

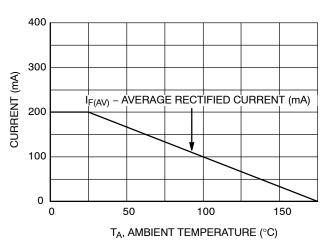


Figure 8. Average Rectified Current (I_{F(AV)}) vs. Ambient Temperature (T_A)

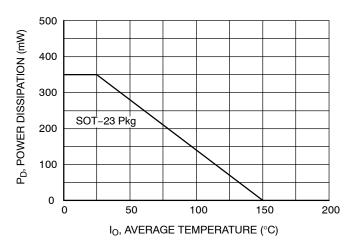


Figure 9. Power Derating Curve

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ORDERING INFORMATION

Part Number	Top Mark	Package	Shipping [†]
MMBD4148SE	D4	SOT-23	3,000 / Tape & Reel
MMBD4148CC	D5	(Pb-Free)	3,000 / Tape & Reel
MMBD4148CA	D6		3,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D



SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

DATE 30 JAN 2018

SCALE 4:1 D - 3X b

TOP VIEW







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

	PROT	RUSIONS, OR GATE BURRS.	
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	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE
OT (1 F O			

SOT-23 (TO-236)

STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
ANODE	SOURCE	CATHODE	CATHODE	2. DRAIN	2. GATE
CATHODE	3. GATE	CATHODE-ANODE	ANODE	3. GATE	ANODE

STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
CATHODE	CATHODE	2. ANODE	CATHODE	2. ANODE	ANODE
ANODE	CATHODE	CATHODE	ANODE	CATHODE-ANOD	E 3. GATE

STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
SOURCE	OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3 DRAIN	3 INPLIT	3 CATHODE	3. SOURCE	3. GATE	NO CONNECTION

STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE	
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